

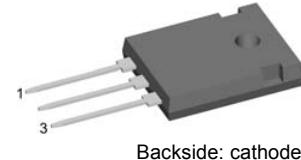
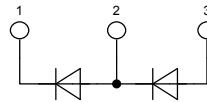
Standard Rectifier

Phase leg

V_{RRM} = 1600 V
I_{FAV} = 2x 45 A
V_F = 1.23 V

Part number

DSP45-16A

**Features / Advantages:**

- Planar passivated chips
- Very low leakage current
- Very low forward voltage drop
- Improved thermal behaviour

Applications:

- Diode for main rectification
- For single and three phase bridge configurations

Package:

- Housing: TO-247
- Industry standard outline
- Epoxy meets UL 94V-0
- RoHS compliant

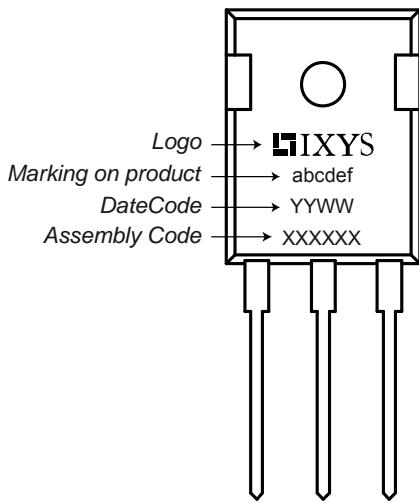
Symbol	Definition	Conditions		Ratings		
		min.	typ.	max.	Unit	
V _{RRM}	max. repetitive reverse voltage		T _{VJ} = 25°C		1600	V
I _R	reverse current	V _R = 1600 V	T _{VJ} = 25°C		20	µA
		V _R = 1600 V	T _{VJ} = 150°C		3	mA
V _F	forward voltage	I _F = 45 A	T _{VJ} = 25°C		1.28	V
		I _F = 90 A			1.37	V
		I _F = 45 A	T _{VJ} = 150°C		1.23	V
		I _F = 90 A			1.35	V
I _{FAV}	average forward current	rectangular d = 0.5	T _C = 130°C		45	A
V _{F0}	threshold voltage	slope resistance } for power loss calculation only	T _{VJ} = 175°C		0.81	V
					9.1	mΩ
R _{thJC}	thermal resistance junction to case				0.55	K/W
T _{VJ}	virtual junction temperature		-40		175	°C
P _{tot}	total power dissipation		T _C = 25°C		270	W
I _{FSM}	max. forward surge current	t = 10 ms (50 Hz), sine	T _{VJ} = 45°C		480	A
		t = 8,3 ms (60 Hz), sine	V _R = 0 V		518	A
		t = 10 ms (50 Hz), sine	T _{VJ} = 150°C		408	A
		t = 8,3 ms (60 Hz), sine	V _R = 0 V		441	A
I ² t	value for fusing	t = 10 ms (50 Hz), sine	T _{VJ} = 45°C		1152	A ² s
		t = 8,3 ms (60 Hz), sine	V _R = 0 V		1120	A ² s
		t = 10 ms (50 Hz), sine	T _{VJ} = 150°C		832	A ² s
		t = 8,3 ms (60 Hz), sine	V _R = 0 V		808	A ² s
C _J	junction capacitance	V _R = 400 V; f = 1 MHz	T _{VJ} = 25°C	18		pF

Symbol	Definition	Conditions	Ratings		
			min.	typ.	max.
I_{RMS}	RMS current	per pin ¹⁾			70 A
R_{thCH}	thermal resistance case to heatsink			0.25 K/W	
T_{stg}	storage temperature		-55		150 °C
Weight				6 g	
M_D	mounting torque		0.8		1.2 Nm
F_c	mounting force with clip		20		120 N

¹⁾ I_{RMS} is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip.

In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

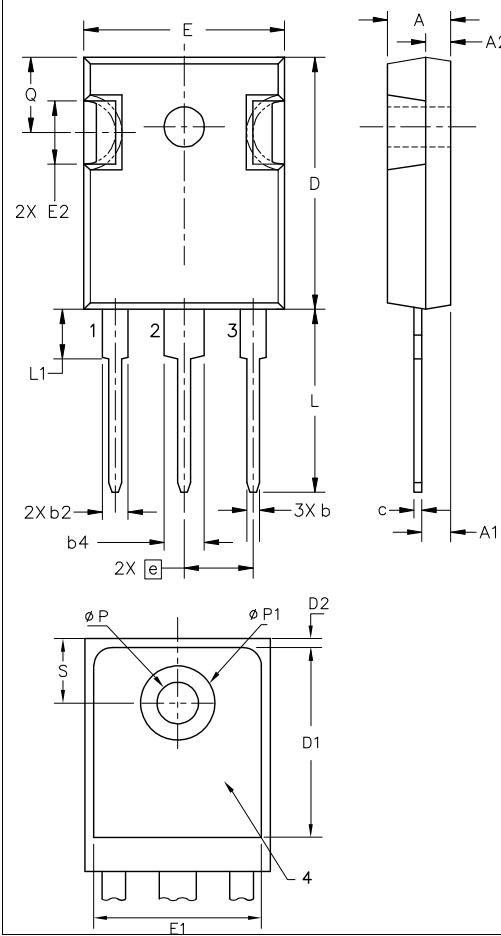
Product Marking



Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Code Key
Standard	DSP45-16A	DSP45-16A	Tube	30	480665

Similar Part	Package	Voltage class
DSP45-16AR	ISOPLUS247 (3)	1600
DSP45-12A	TO-247AD (3)	1200

Outlines TO-247



Sym.	Inches min. max.	Millimeter min. max.
A	0.185 0.209	4.70 5.30
A1	0.087 0.102	2.21 2.59
A2	0.059 0.098	1.50 2.49
D	0.819 0.845	20.79 21.45
E	0.610 0.640	15.48 16.24
E2	0.170 0.216	4.31 5.48
e	0.215 BSC	5.46 BSC
L	0.780 0.800	19.80 20.30
L1	- 0.177	- 4.49
Ø P	0.140 0.144	3.55 3.65
Q	0.212 0.244	5.38 6.19
S	0.242 BSC	6.14 BSC
b	0.039 0.055	0.99 1.40
b2	0.065 0.094	1.65 2.39
b4	0.102 0.135	2.59 3.43
c	0.015 0.035	0.38 0.89
D1	0.515 -	13.07 -
D2	0.020 0.053	0.51 1.35
E1	0.530 -	13.45 -
Ø P1	- 0.29	- 7.39

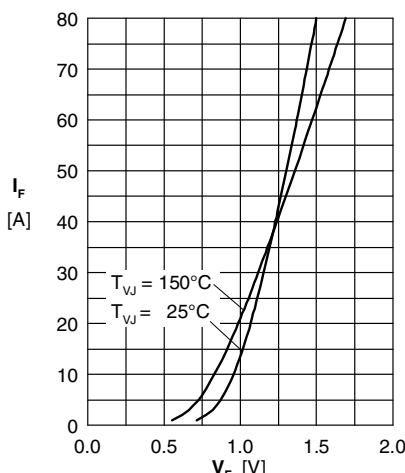


Fig. 1 Forward current versus voltage drop per diode

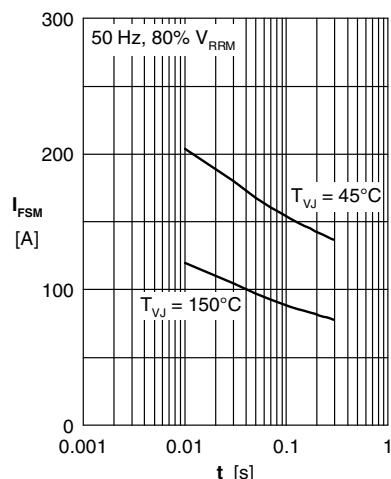


Fig. 2 Surge overload current

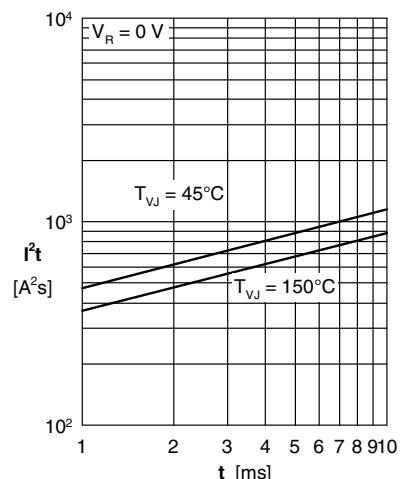
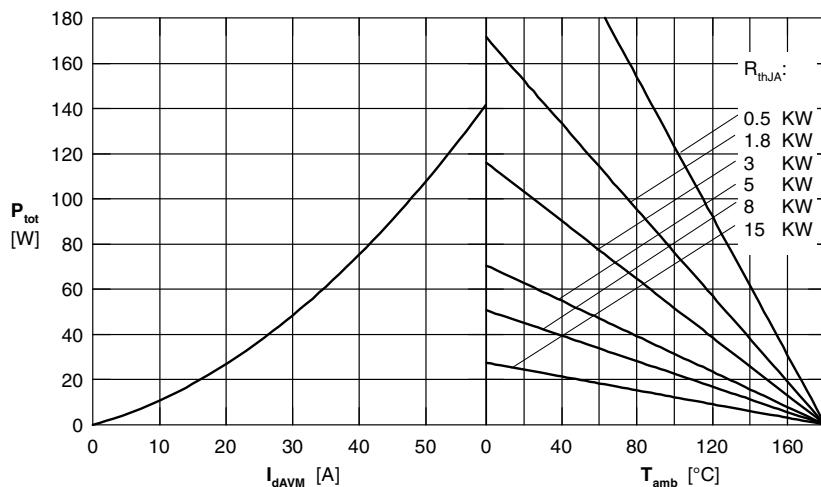
Fig. 3 I^2t versus time per diode

Fig. 4 Power dissipation vs. direct output current & ambient temperature, sine 180°

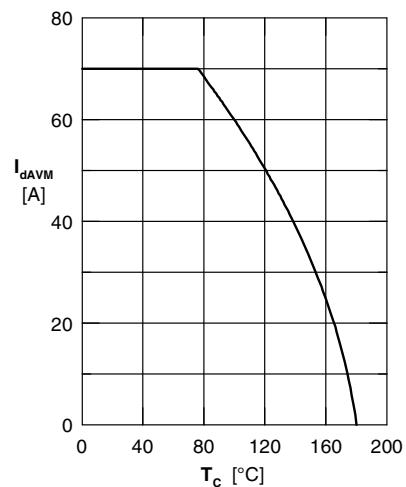


Fig. 5 Max. forward current versus case temperature, sine180°

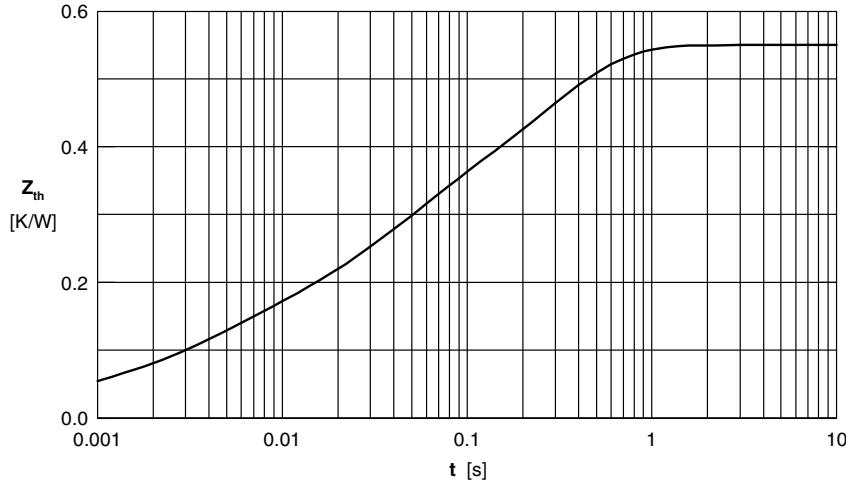


Fig. 6 Transient thermal impedance junction to case

i	R _i	τ_i
1	0.033	0.0006
2	0.095	0.0039
3	0.164	0.033
4	0.258	0.272